



# NPM

NEXT PRODUCTION MODULAR

## Manufacturing Process Innovation



Model ID **NPM-D3A**  
Model No. NM-EJM6E



\*It may not conform to Machinery Directive and EMC Directive in case of optional configuration and custom-made specification.

機 種 名		NPM-D3A
PCB dimensions <sup>*1</sup>	Dual-lane mode	L 50 mm × W 50 mm ~ L 510 mm × W 300 mm
	Single-lane mode	L 50 mm × W 50 mm ~ L 510 mm × W 590 mm
PCB exchange time	Dual-lane mode	0 s* *No 0s when cycle time is 3.6 s or less
	Single-lane mode	3.6 s* *When selecting short conveyors
Electric source		3-phase AC 200, 220, 380, 400, 420, 480 V 2.7 kVA
Pneumatic source <sup>*2</sup>		0.5 MPa, 100 L/min (A.N.R.)
Dimensions <sup>*2</sup>		W 832 mm × D 2 652 mm <sup>*3</sup> × H 1 444 mm <sup>*4</sup>
Mass		1 680 kg (Only for main body; This differs depending on the option configuration.)

Placement head		Lightweight 16-nozzle head V3 (Per head)	
		High production mode[ON]	High production mode[OFF]
Max. speed		46 000 cph (0.078 s/ chip)	38 000 cph (0.095 s/ chip)
Placement accuracy (Cpk ≥ 1)		± 37 μm / chip	± 30 μm / chip (± 25 μm / chip <sup>*5</sup> )
Component dimensions (mm)		0402 chip <sup>*6</sup> ~ L 6 × W 6 × T 3	03015 <sup>*6</sup> / 0402 chip <sup>*6</sup> ~ L 6 × W 6 × T 3
Component supply	Taping	Tape: 4 / 8 / 12 / 16 mm	
		Max. 68(4, 8 mm tape, Small reel)	

\* Placement tact time, inspection time and accuracy values may differ slightly depending on conditions  
\* Please refer to the specification booklet for details.

\*1 : Due to a difference in PCB transfer reference, a direct connection with NPM (NM-EJM5E) / NPM-W (NM-EJM2D) / NPM-W2 (NM-EJM7D) dual lane specs cannot be established.

\*2 : Only for main body

\*3 : Dimension D including feeder cart

\*4 : Excluding the monitor, signal tower and ceiling fan cover.

\*5 : ± 25 μm placement support option. (Under conditions specified by Panasonic)

\*6 : The 03015/0402 mm chip requires a specific nozzle/feeder.

\*7 : Support for 03015 mm chip placement is optional. (Under conditions specified by Panasonic : Placement accuracy ± 30 μm / chip)